

LINEAR TECHNOLOGY MATERIALS DECLARATION

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(Engineering Calculation)

DDPAK

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TOTAL MASS (g) : 1.407646

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|---------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.005956 | 1000000 | 4231.17822266 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.852419 | 998500 | 605563.5625 | | |
| | | Iron (Fe) | 7439-89-6 | 0.000000 | 0 | 0 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000000 | 0 | 0 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000000 | 0 | 0 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.001281 | 1500 | 910.030029297 | | |
| Lead Frame Total: | | | | 0.853700 | 1000000 | 606473.5625 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.010925 | 1000000 | 7761.12695312 | | |
| | | External Plating Total: | | | | 0.010925 | 1000000 | 7761.12695312 |
| | | Inter. Plating Ni | 7440-02-0 | 0.005000 | 714285.6875 | 3552.02978516 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.002000 | 285714.28125 | 1420.81201172 | | |
| Internal Plating Total: | | | | 0.007000 | 1000000 | 4972.84228516 | | |
| Die Attach | 95Pb / 5 Sn | Silver (Ag) | 7440-22-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000129 | 50000 | 91.642364502 | | |
| | | Lead (Pb) | 7439-92-1 | 0.002453 | 950000 | 1742.62585449 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000000 | 0 | 0 | | |
| Die Attach Total: | | | | 0.002582 | 1000000 | 1834.26831055 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.054044 | 103000 | 38393.1796875 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.469607 | 895000 | 333611.59375 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.001049 | 2000 | 745.215881348 | | |
| | | Encapsulation Total: | | | | 0.524700 | 1000000 | 372750 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.002783 | 1000000 | 1977.05981445 | | |
| | | | | | TOTAL MASS (g) : | 1.407646 | | |